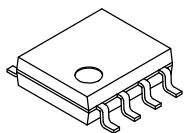


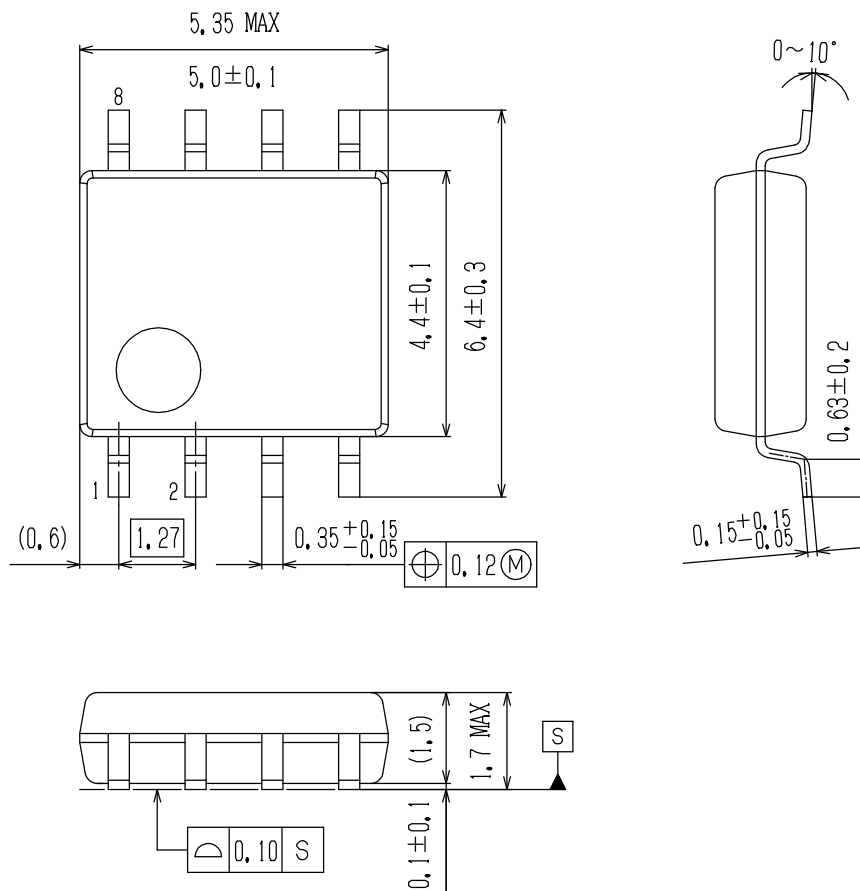
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



SOIC8 W / MFP8 (225 mil)
CASE 751BV
ISSUE O

DATE 29 FEB 2012



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